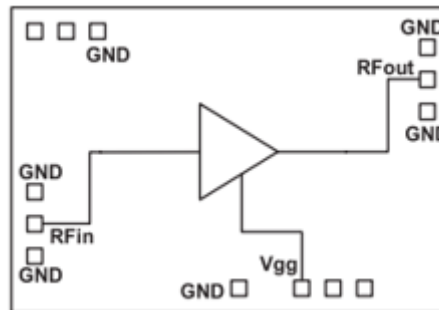


Features

- Frequency: DC-35GHz
- Gain: 16dB
- Noise Figure: 2dB
- P1dB: +15dBm
- Power Supply: +3V@150 mA
- I/O 50 ohm matching: VSWR<1.5

Functional Block Diagram

Typical Applications

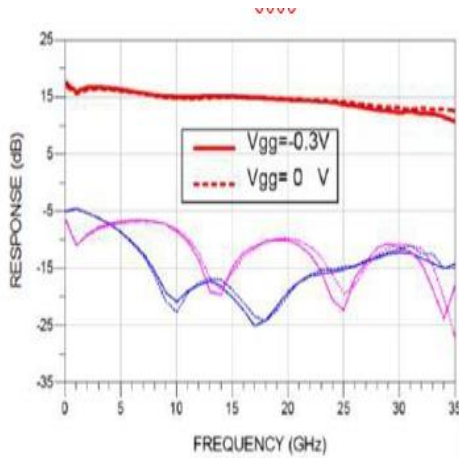
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

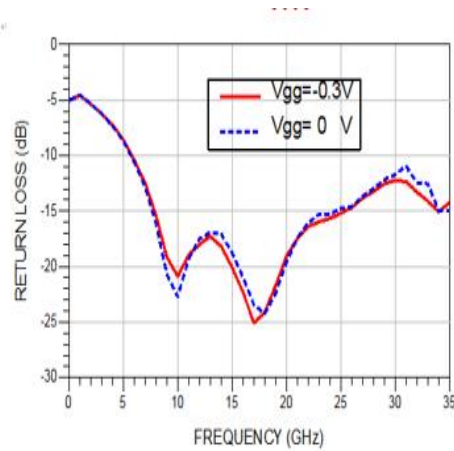
TA = +25°C, Vdd = +3V, Vgg=-0.3V (0V also works fine) (On-wafer Measurement Results)

Parameters	Min.	Typ.	Max.	Units
Frequency	DC-35			GHz
Gain	11	16		dB
P1dB	11	16		dBm
Noise Figure	1.8	2		dB
Input Return Loss	8	10		dB
Output Return Loss	8	15		dB
Operating Current (@Vdd = 3V)		150		mA

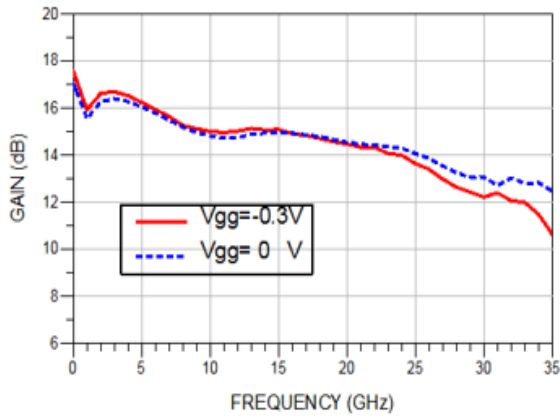
Frequency response vs. V_{gg}



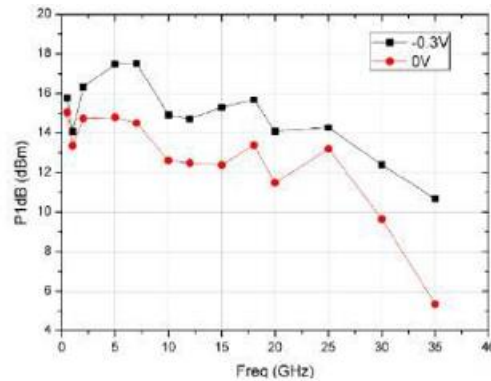
Output Return Loss vs. V_{gg}



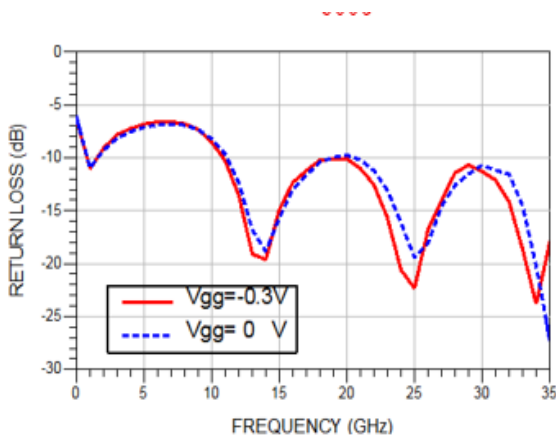
Gain vs. V_{gg}



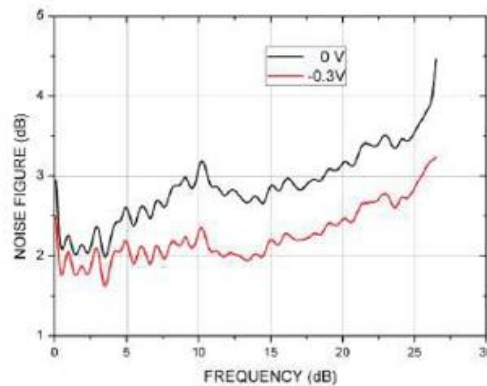
P1dB vs. V_{gg}



Input Return Loss vs. V_{gg}

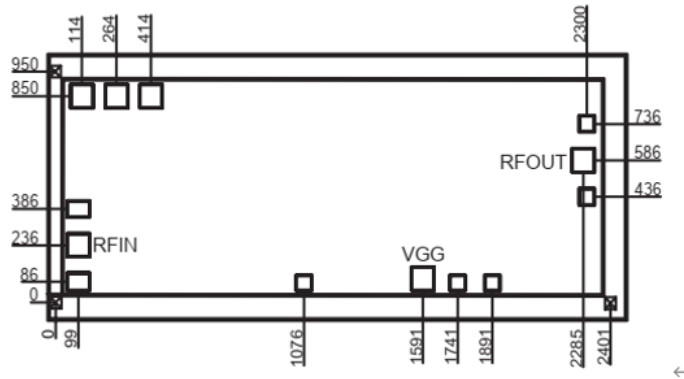


Noise Figure vs. V_{gg}

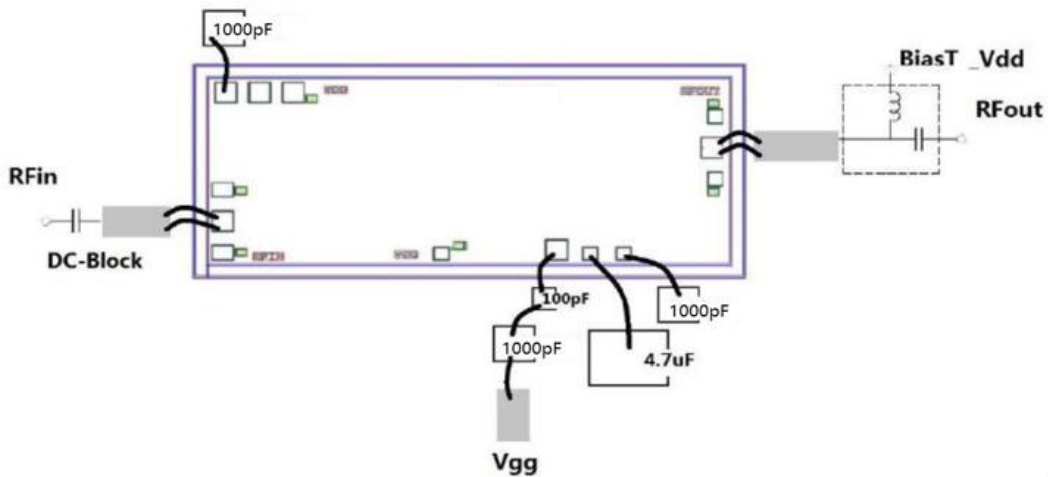




Outline Drawing: All Dimensions in μm



Assembly Drawing (Bond testing)



Notes:

1. Die thickness: 100 μm
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads
7. No DC Block
8. Input/Output use two 25 μm gold wire, length less than 250 μm is recommended.

Maximum Ratings:

1. Supply voltage: +3V
2. Operating temperature: -55 $^{\circ}\text{C}$ to +85 $^{\circ}\text{C}$
3. Storage temperature: -65 $^{\circ}\text{C}$ to +150 $^{\circ}\text{C}$